



DUAL N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(ON)} Max	I _D T _A = +25°C
20V	$20.2m\Omega$ @ $V_{GS} = 4.5V$	7.5A
200	23.5mΩ @ $V_{GS} = 2.5V$	7.0A

Description

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

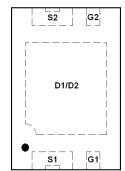
- Power Management Functions
- Battery Pack
- Load Switch

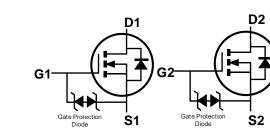
Features

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: U-DFN2030-6
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram Below
- Weight: 0.012 grams (Approximate)





U-DFN2030-6





Bottom View

Top View

Equivalent Circuit

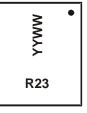
Ordering Information (Note 4)

Part Number	Case	Packaging
DMN2028UFU-7	U-DFN2030-6	3000 / Tape & Reel
DMN2028UFU-13	U-DFN2030-6	10000 / Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



R23 = Product Type Marking Code YYWW = Date Code Marking YY = Last Digit of Year (ex: 14 for 2014) WW = Week Code (01 to 53)



Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V_{DSS}	20	V
Gate-Source Voltage			V _{GSS}	±10	V
Continuous Durin Comment (Note C) V	Steady State	$T_A = +25$ °C $T_A = +70$ °C	ID	7.5 6.0	А
Continuous Drain Current (Note 6) V _{GS} = 4.5V	t<10s	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	9.9 7.9	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I _{DM}	40	Α
Avalanche Current (Note 7) L = 0.1mH			I _{AS}	12	Α
Avalanche Energy (Note 7) L = 0.1mH			Eas	8	mJ

Thermal Characteristics

Characteristic		Symbol	Value	Unit	
Total Power Dissipation (Note 5)	T _A = +25°C	P _D	0.9	W	
Thermal Basistanes, Junction to Ambient (Note 5)	Steady State	D	144	°C/W	
Thermal Resistance, Junction to Ambient (Note 5)	t<10s	$R_{\theta JA}$	84		
Total Power Dissipation (Note 6)	$T_A = +25^{\circ}C$	P _D	1.8	W	
Thermal Desistance Junction to Ambient (Note C)	Steady State	Б.	69		
Thermal Resistance, Junction to Ambient (Note 6)	t<10s	$R_{\theta JA}$	40	°C/W	
Thermal Resistance, Junction to Case		$R_{ heta JC}$	8.4		
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C	

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV _{DSS}	20	I	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}		I	1	μA	$V_{DS} = 20V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}		1	±10	μΑ	$V_{GS} = \pm 8V$, $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V _{GS(TH)}	0.5	_	1.0	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
			15.3	20.2		$V_{GS} = 4.5V$, $I_{D} = 4.5A$	
			15.4	22.5		$V_{GS} = 4.0V, I_D = 4.0A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	_	16.7	23.0	mΩ	$V_{GS} = 3.1V, I_D = 4.0A$	
			18.3	23.5		$V_{GS} = 2.5V, I_D = 3.5A$	
			24.2	30.0		$V_{GS} = 1.8V, I_D = 3.5A$	
Diode Forward Voltage	V_{SD}		0.7	1.2	V	$V_{GS} = 0V$, $I_S = 1A$	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	C _{iss}	_	887	_		.,	
Output Capacitance	Coss	_	91	_	pF	$V_{DS} = 10V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	C _{rss}		37	_		1 – 1.01/11/12	
Gate Resistance	R_g	_	191	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Q_g	_	10	_			
Total Gate Charge (V _{GS} = 8V)	Qg		18.4	_	nC	V _{DS} = 10V. I _D = 6.5A	
Gate-Source Charge	Q_{gs}	_	1.3	_	110	VDS = 10V, ID = 6.5A	
Gate-Drain Charge	Q_{gd}		1.8	_			
Turn-On Delay Time	t _{D(ON)}	_	53	_			
Turn-On Rise Time	t _R		66	_	20	$V_{DS} = 10V, V_{GS} = 4.5V,$	
Turn-Off Delay Time	t _{D(OFF)}	_	619	_	ns	$R_G = 6\Omega$, $R_L = 10\Omega$, $I_D = 1A$	
Turn-Off Fall Time	t _F	_	197	_			
Reverse Recovery Time	t _{RR}	_	119	_	ns	I _F = 4A, di/dt = 100A/μs	
Reverse Recovery Charge	Q _{RR}		96	_	nC	I _F = 4A, di/dt = 100A/μs	

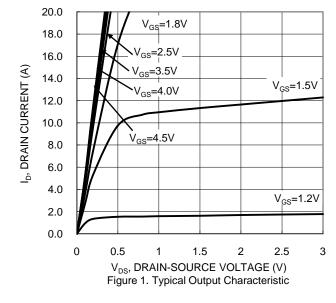
5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate. Notes:

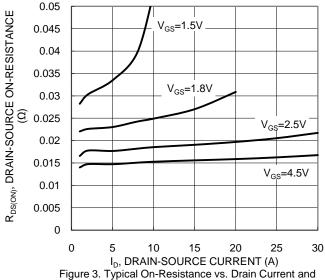
7. I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep $T_J = +25^{\circ}C$.

8. Short duration pulse test used to minimize self-heating effect.

9. Guaranteed by design. Not subject to product testing.







Gate Voltage

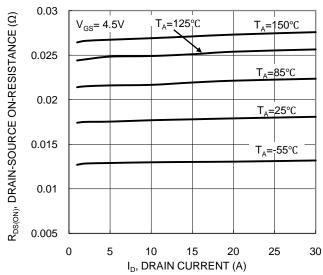
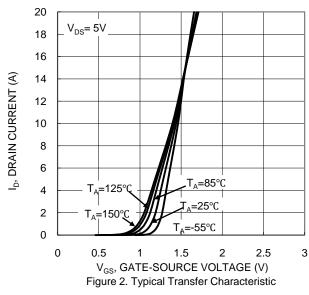
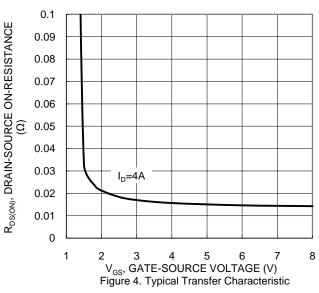


Figure 5. Typical On-Resistance vs. Drain Current and Temperature





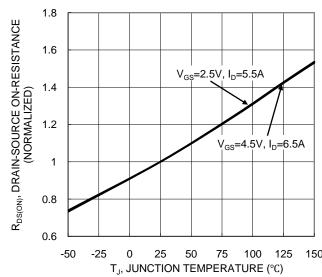
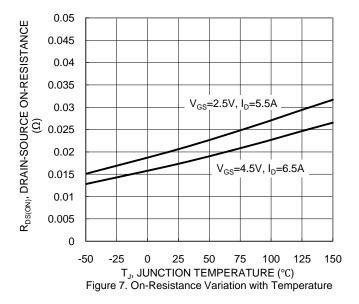
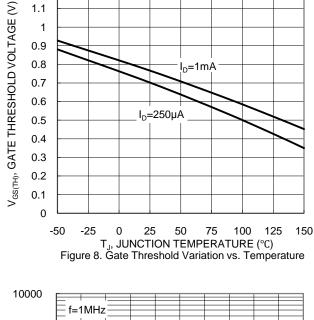


Figure 6. On-Resistance Variation with Temperature



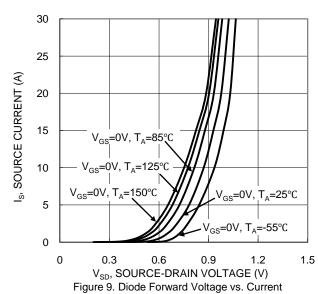


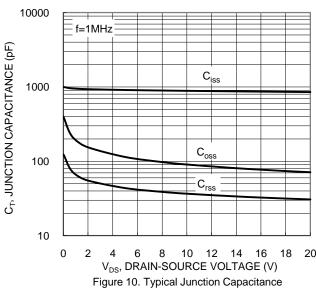


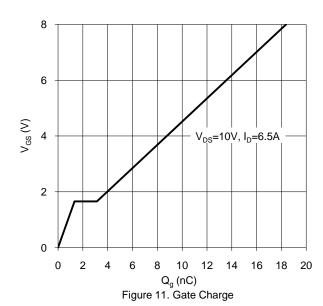


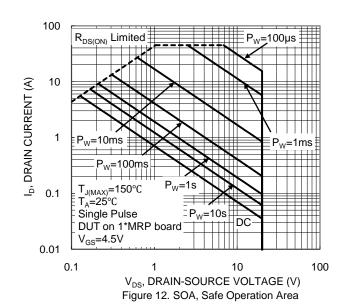
1.2

1.1

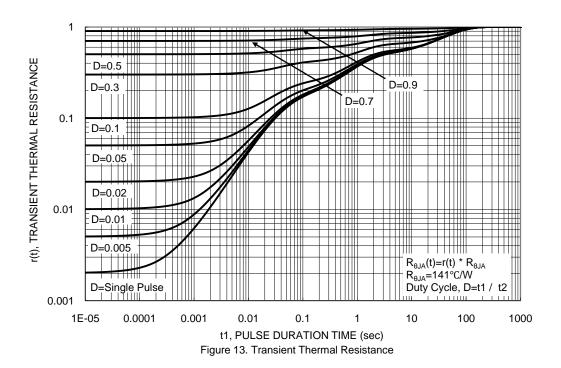






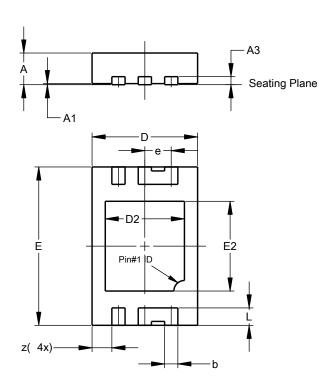






Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

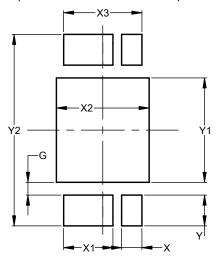


U-DFN2030-6 (Type B)					
Dim	Min	Max	Тур		
Α	0.55	0.65	0.60		
A1	0.00	0.05	0.02		
A3			0.15		
b	0.20	0.30	0.25		
D	1.95	2.05	2.00		
D2	1.40	1.60	1.50		
Е	2.95	3.05	3.00		
E2	1.65	1.75	1.70		
e			0.50		
L	0.28	0.38	0.33		
Z			0.375		
All Dimensions in mm					



Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)		
G	0.220		
X	0.350		
X1	0.850		
X2	1.600		
Х3	1.350		
Y	0.530		
Y1	1.800		
Y2	3.300		

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